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Product Change Notification - GBNG-28HRUQ041 (Printer Friendly)

Date:

12 Apr 2017

Product Category:

Power Management - System Supervisors/Voltage Detectors; Voltage References

Notification subject:

CCB 2840 Initial Notice: Qualification of JCET as an additional assembly site for selected products of the 120K wafer technology available in 3L SOT-23 package using CuPdAu bond wire.

Notification text:**PCN Status:**

Initial notification.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of JCET as an additional assembly site for selected products of the 120K wafer technology available in 3L SOT-23 package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at MTAI, ATES, NSEB or UNIS using gold (Au) bond wire and G600 molding compound material

Post Change:

Assembled at MTAI, ATES, NSEB and UNIS using gold (Au) bond wire and G600 molding compound material or assembled at JCET using palladium coated copper with gold flash (CuPdAu) bond wire and ELER-8-100HFE molding compound material.

Pre and Post Change Summary:

	Pre Change				Post Change				
Assembly Site	MTAI	ATES	NSEB	UNIS	MTAI	ATES	NSEB	UNIS	JCET
Paddle size	64x38	64x38	72x40	57x35	64x38	64x38	72x40	57x35	75x42
Lead frame material	CDA194	CDA194	CDA194	CDA194	CDA194	CDA194	CDA194	CDA194	CDA194
Wire material	Au	Au	Au	Au	Au	Au	Au	Au	CuPdAu
Die attach material	8390A	84-1 LMISR4	84-1 LMISR4	84-1 LMISR4	8390A	84-1 LMISR4	84-1 LMISR4	84-1 LMISR4	84-1 LMISR4
Mold compound material	G600	G600	G600	G600	G600	G600	G600	G600	ELER-8-100HFE

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying JCET as an additional assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

June 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	April 2017				-->	June 2017			
	14	15	16	17		23	24	25	26
Initial PCN Issue Date		X							
Qual Report Availability									X
Final PCN Issue Date									X

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

April 12, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_GBNG-28HRUQ041_ Qual Plan.pdf](#)

[PCN_GBNG-28HRUQ041_Affected CPN.pdf](#)

[PCN_GBNG-28HRUQ041_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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